OPA1633
ZHCSRO1A – FEBRUARY 2023 – REVISED JULY 2023

OPA1633 高性能、全差分音频运算放大器

1 特性

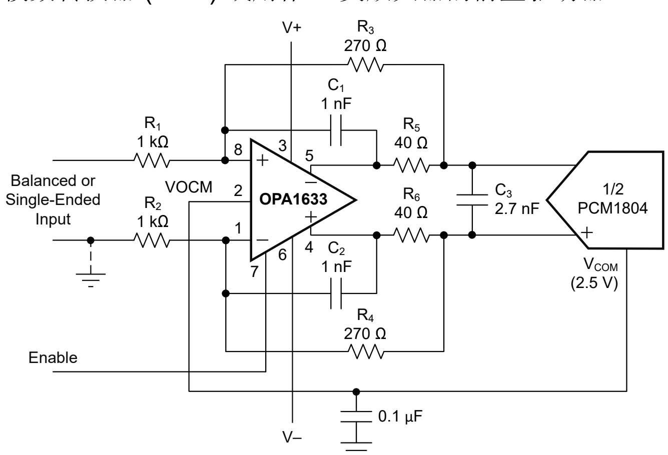
- 出色的音质
- 超低失真：132dB
- 低噪声：1.1nV/√Hz
- 高速：
  - 压摆率：80 V/μs
  - 增益带宽积：200MHz
- 完全差分架构：
  - 平衡输入和输出将单端输入转换为平衡差分输出
- 宽电源电压范围：±2.5V 至 ±17.5V
- 关断电流：0.77 mA (V_S = ± 5V)
- 温度范围：–40°C 至 +85°C
- 封装：HVSSOP-8、SOIC-8

2 应用

- 专业音频混合器或控制平面
- 专业麦克风和无线系统
- 专业扬声器系统
- 专业音频放大器
- 条形音箱
- 转盘
- 专业摄像机
- 吉他和其他乐器放大器
- 数据采集 (DAQ)
- 引脚兼容型升级至 OPA1632

3 说明

OPA1633 是一款全差分放大器，旨在驱动高性能音频模数转换器 (ADC) 或用作 D 类放大器的前置驱动器。



应用示意图

OPA1633 可实现卓越的音频质量、极低的噪声、大输出电压摆幅和高电流驱动。OPA1633 具有 200MHz 的出色增益带宽以及 80V/μs 的超快压摆率，可实现极低的失真。非常低的输入电压噪声 1.1nV/√Hz 可进一步提供更大信噪比和动态范围。

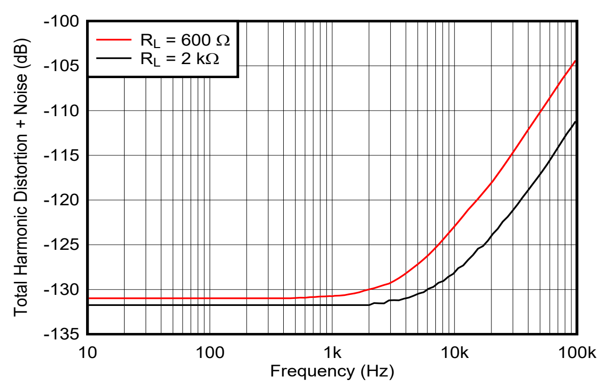
全差分架构的灵活性有助于轻松实现单端到全差分输出转换。差分输出可减少偶次谐波并最大限度地减少共模噪声干扰。OPA1633 在用于驱动高性能音频 ADC（如 PCM1804）时可提供卓越的性能。添加了关断功能以在器件未使用时节省电量。

OPA1633 可在 −40°C 至 +85°C 的温度范围内正常运行，采用 SO-8 封装和热增强型 HVSSOP PowerPAD ™ 集成电路封装。

封装信息

器件型号	封装(1)	封装尺寸(2)
OPA1633	D（SOIC，8）	4.9 mm × 6 mm
	DGN（HVSSOP，8）	3 mm × 4.9 mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。
(2) 封装尺寸（长 x 宽）为标称值，并包括引脚（如适用）。



THD+N 与频率间的关系

English Data Sheet: SBOSAC7

Table of Contents

4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision * (February 2023) to Revision A (June 2023)	Page
• 将数据表状态从“预告信息（预发布）”更改为“量产数据（正在供货）”	1

5 Pin Configuration and Functions

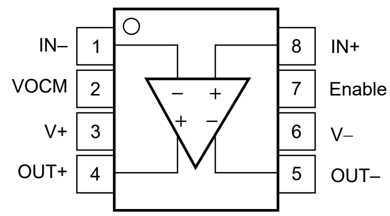


图 5-1. D Package, 8-Pin SOIC or DGN[(1)] Package, 8-Pin HVSSOP (Top View)

表 5-1. Pin Functions

PIN		TYPE[(2)]	DESCRIPTION
NAME	NO.		
Enable	7	I	Active-high enable pin
V+	3	I/O	Positive supply voltage pin
V-	6	I/O	Negative supply voltage pin
IN+	8	I	Positive input voltage pin
IN –	1	I	Negative input voltage pin
VOCM	2	I	Output common-mode control voltage pin
OUT+	4	O	Positive output voltage pin
OUT –	5	O	Negative output voltage pin

(1) Solder the exposed DGN package thermal pad to a heat-spreading power or ground plane. This pad is electrically isolated from the die, but must be connected to a power or ground plane and not floated.
(2) I = input, O = output.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)[(1)] [(2)]

		MIN	MAX	UNIT
V_S	Supply voltage		±18.5	V
	Supply turn on and turn off dV/dT[(3)]		1.7	V/µs
V_I	Input voltage		$\pm V_S$	V
I_O	Output current		150	mA
I_{IN}	Continuous input current		10	mA
V_{ID}	Differential input voltage		±1.5	V
T_J	Junction temperature		150	°C
T_A	Ambient temperature	–40	85	°C
T_{stg}	Storage temperature	–65	150	°C

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If briefly operating outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) The OPA1633 HVSSOP PowerPAD integrated circuit package incorporates a thermal pad on the underside of the chip. This thermal pad acts as a heat sink and must be connected to a thermally-dissipative plane for proper power dissipation. Failure to do so can result in exceeding the maximum junction temperature, which can permanently damage the device. See TI technical brief SLMA002 for more information about using the thermally-enhanced PowerPAD integrated circuit package.
(3) Stay below this specification to make sure that the edge-triggered ESD absorption devices across the supply pins remain off.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001[(1)]	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002[(2)]	±1500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_S	Supply voltage	Dual	±2	±17.5	V
		Single	4	35	
T_A	Ambient temperature		−40	85	°C

6.4 Thermal Information

THERMAL METRIC[(1)]		OPA1633		UNIT
		D (SOIC)	DGN (HVSSOP)	
		8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	126.3	57.6	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	67.3	76.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	69.8	30.0	°C/W
ψ_{JT}	Junction-to-top characterization parameter	19.5	4.0	°C/W
ψ_{JB}	Junction-to-board characterization parameter	69.0	29.9	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	14.3	°C/W

(1) For information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Electrical Characteristics

at V_S = ±15 V, R_F = 390 Ω, R_L = 800 Ω, and G = +1 (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFFSET VOLTAGE							
V_{OS}	Input offset voltage				0.2	2	mV
dV_{OS}/dT	Offset voltage drift				±0.6		μV/°C
PSRR	Power supply rejection ratio				13	100	μV/V
INPUT BIAS CURRENT							
I_B	Input bias current				6.8	11.5	μA
I_{OS}	Input offset current				±20	±400	nA
NOISE							
e_N	Input voltage noise density		f = 10 kHz		1.1		nV/√Hz
i_N	Input current noise density		f = 10 kHz		1.3		pA/√Hz
INPUT VOLTAGE							
V_{CM}	Common-mode voltage			(V−) + 1.5		(V+) − 1	
CMRR	Common-mode rejection ratio			80	100		dB
INPUT IMPEDANCE							
	Input impedance	Common-mode	Measured into each input pin		320 || 1.3		MΩ || pF
	Input impedance	Differential	Measured into each input pin		12 || 2.3		kΩ || pF
OPEN-LOOP GAIN							
A_{OL}	Open-loop gain			91	97		dB
FREQUENCY RESPONSE							
SSBW	Small signal bandwidth		G = +1, R_F= 348 Ω		200		MHz
SSBW	Small signal bandwidth	(V_O = 100 mV_{PP}, peaking < 0.5 dB)	G = +2, R_F = 602 Ω		117		MHz
SSBW	Small signal bandwidth	(V_O = 100 mV_{PP}, peaking < 0.5 dB)	G = +5, R_F = 1.5 kΩ		53		MHz
SSBW	Small signal bandwidth	(V_O = 100 mV_{PP}, peaking < 0.5 dB)	G = +10, R_F = 3.01 kΩ		26		MHz
	Bandwidth for 0.1-dB flatness		G = +1, V_O = 100 mV_{PP}		40		MHz
	Peaking at a gain of 1		V_O = 100 mV_{PP}		0.25		dB
LSBW	Large-signal bandwidth		G = +2, V_O = 20 V_{PP}		3		MHz
SR	Slew rate (25% to 75%)		G = +1		80		V/μs
	Rise and fall time		G = +1, V_O = 5-V step		62		ns
t_s	Settling time	To 0.1%	G = +1, V_O = 2-V step		30		ns
t_s	Settling time	To 0.01%	G = +1, V_O = 2-V step		40		ns
THD+N	Total harmonic distortion + noise	Differential input/output	G = +1, f = 1 kHz, V_O = 3 V_{RMS}, R_L = 600 Ω		131		dB
THD+N	Total harmonic distortion + noise	Differential input/output	G = +1, f = 1 kHz, V_O = 3 V_{RMS}, R_L = 2 kΩ		132		dB
THD+N	Total harmonic distortion + noise	Single-ended in/differential out	G = +1, f = 1 kHz, V_O = 3 V_{RMS}, R_L = 600 Ω		131		dB
THD+N	Total harmonic distortion + noise	Single-ended in/differential out	G = +1, f = 1 kHz, V_O = 3 V_{RMS}, R_L = 2 kΩ		132		dB
IMD	Intermodulation distortion	Differential input/output	G = +1, SMPTE/DIN, V_O = 2 V_{PP}, R_L = 600 Ω		125		dB
IMD	Intermodulation distortion	Differential input/output	G = +1, SMPTE/DIN, V_O = 2 V_{PP}, R_L = 2 kΩ		125		dB
IMD	Intermodulation distortion	Single-ended in/differential out	G = +1, SMPTE/DIN, V_O = 2 V_{PP}, R_L = 600 Ω		125		dB
IMD	Intermodulation distortion	Single-ended in/differential out	G = +1, SMPTE/DIN, V_O = 2 V_{PP}, R_L = 2 kΩ		125		dB
	Headroom		THD < 0.01%, R_L = 2 kΩ		40		V_{PP}

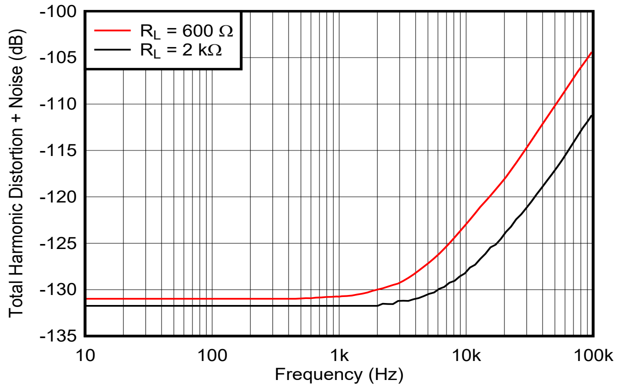
6.5 Electrical Characteristics (continued)

at V_S = ±15 V, R_F = 390 Ω, R_L = 800 Ω, and G = +1 (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
OUTPUT						
V_O	Voltage output swing	R_L = 1 kΩ	(V+) − 1.9		(V−) + 1.9	V
I_O	Output current		65	85		mA
	Closed-loop output impedance	G = +1, f = 100 kHz		0.1		Ω
POWER DOWN						
	Enable voltage threshold			(V−) + 1.45	(V−) + 1.5	V
	Disable voltage threshold		(V−) + 0.8	(V−) + 1.4		V
I_{SD}	Shutdown current	V_S = ±5 V, V_{Enable} = −5 V		0.77		mA
		V_S = ±15 V, V_{Enable} = −15 V		1.4		
	Turn-on delay	Time for I_Q to reach 50%		0.12		µs
	Turn-off delay	Time for I_Q to reach 50%		0.03		µs
POWER SUPPLY						
I_Q	Quiescent current			11	13.2	mA

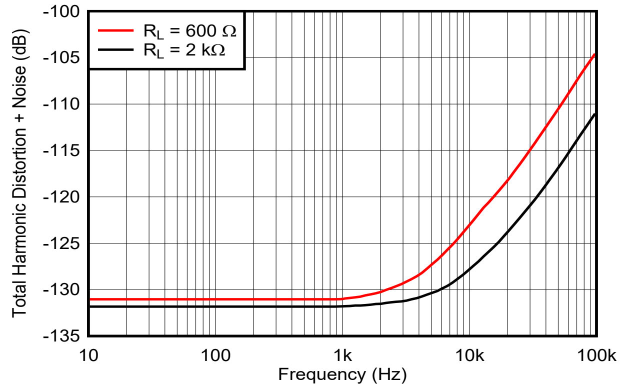
6.6 Typical Characteristics

at T_A = 25°C, V_S = ±15 V, R_F = 348 Ω, G = +1, and R_L = 2 kΩ (unless otherwise noted)



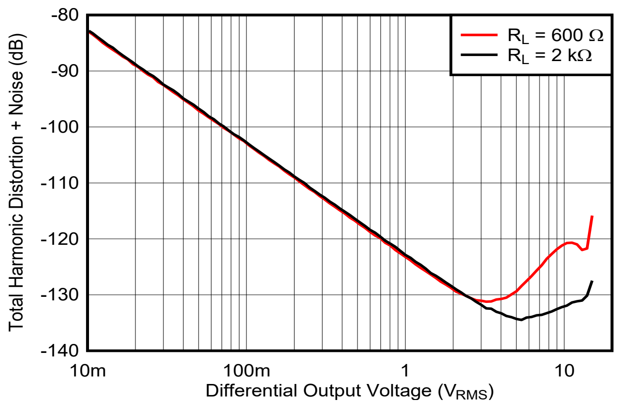
V_O = 3 V_{RMS}, differential input/output

图 6-1. THD + Noise vs Frequency



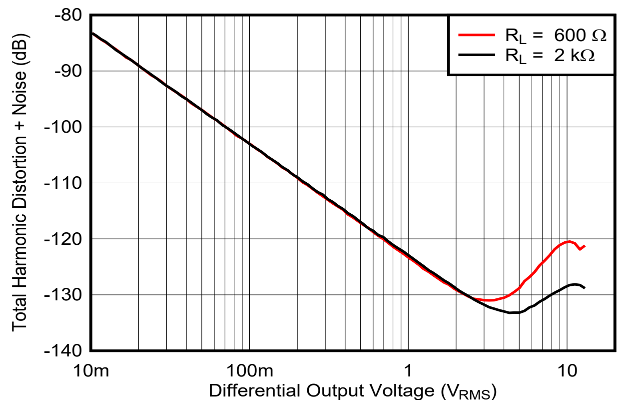
V_O = 3 V_{RMS}, single-ended input to differential output

图 6-2. THD + Noise vs Frequency



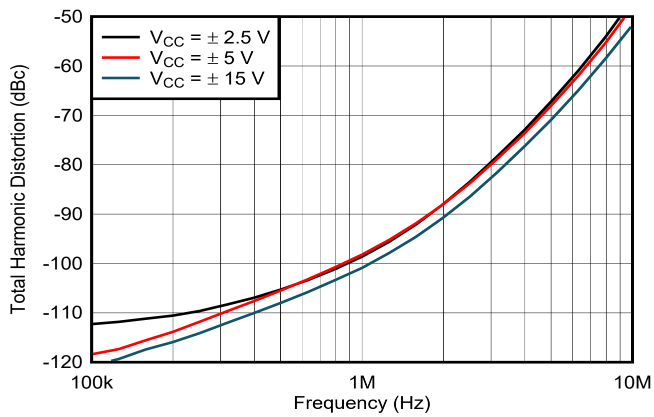
f = 1 kHz, differential input/output

图 6-3. THD + Noise vs Output Voltage



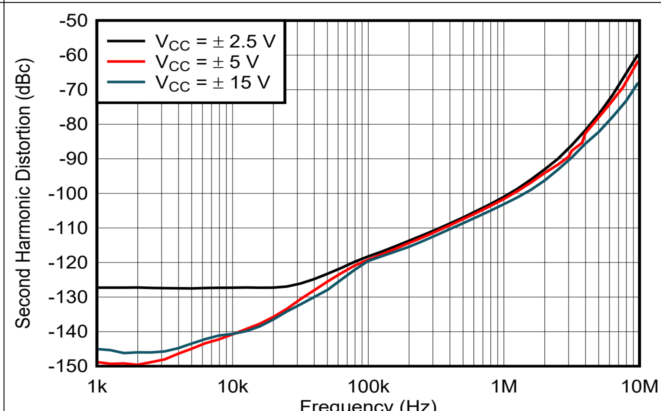
f = 1 kHz, single-ended input to differential output

图 6-4. THD + Noise vs Output Voltage



V_{OUT} = 2 V_{PP}

图 6-5. Total Harmonic Distortion vs Frequency

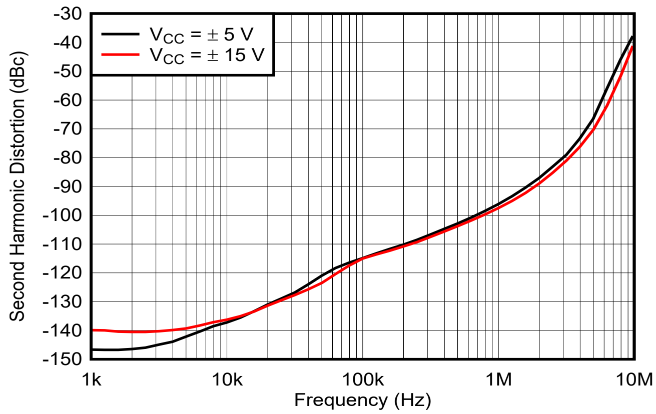


V_{OUT} = 2 V_{PP}, single-ended input, differential output

图 6-6. Second-Harmonic Distortion vs Frequency

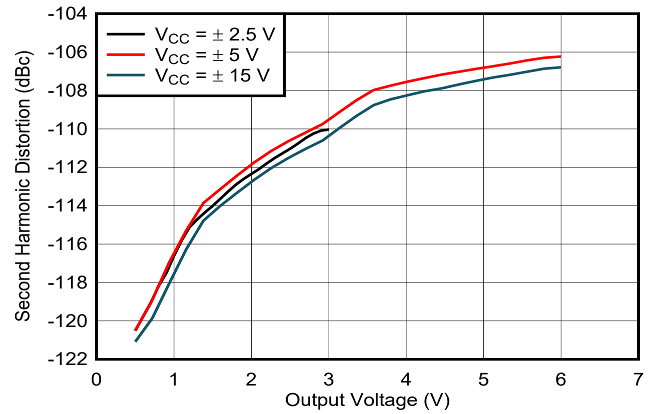
6.6 Typical Characteristics (continued)

at T_A = 25°C, V_S = ±15 V, R_F = 348 Ω, G = +1, and R_L = 2 kΩ (unless otherwise noted)



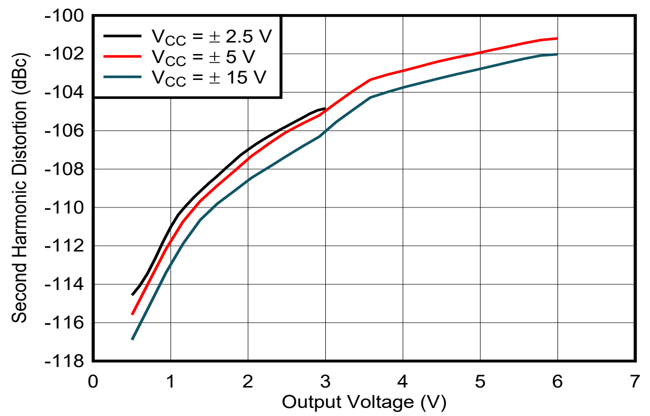
V_{OUT} = 4 V_{PP}, single-ended input, differential output

图 6-7. Second-Harmonic Distortion vs Frequency



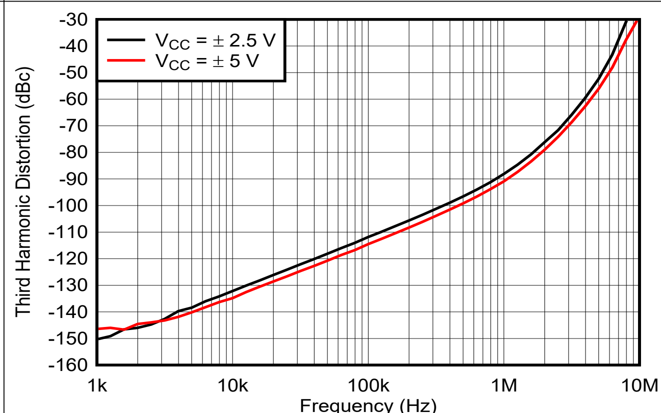
f = 250 kHz, single-ended input, differential output

图 6-8. Second-Harmonic Distortion vs Output Voltage



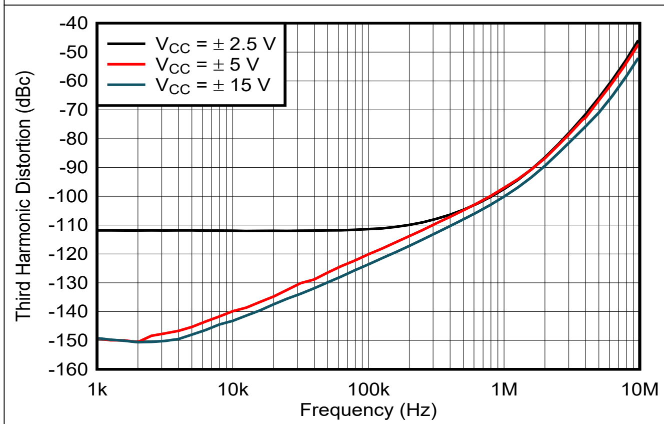
f = 500 kHz, single-ended input, differential output

图 6-9. Second-Harmonic Distortion vs Output Voltage



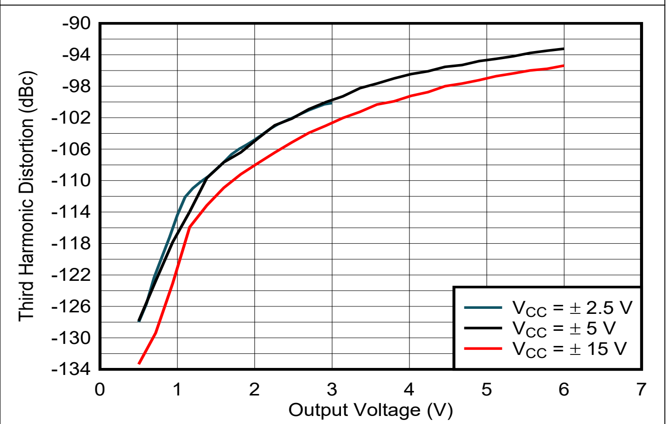
V_{OUT} = 4 V_{PP}, single-ended input, differential output

图 6-10. Third-Harmonic Distortion vs Frequency



v_{out} = 2 v_{pp}, single-ended input, differential output

图 6-11. Third-Harmonic Distortion vs Frequency

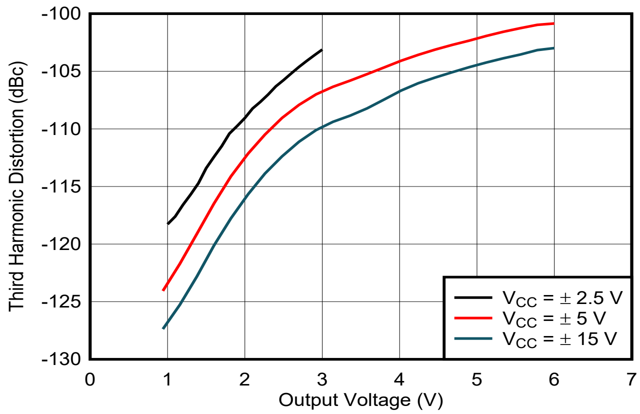


f = 500 kHz, single-ended input, differential output

图 6-12. Third-Harmonic Distortion vs Output Voltage

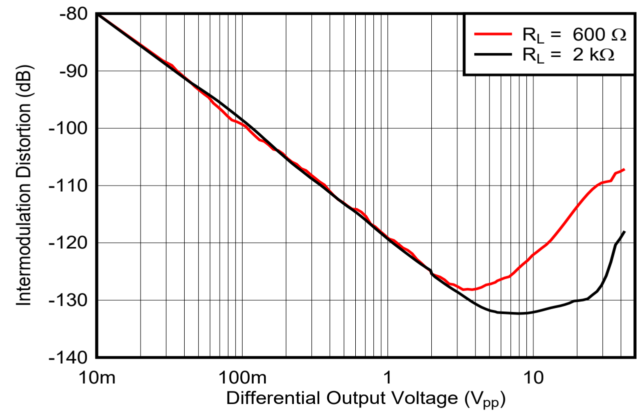
6.6 Typical Characteristics (continued)

at T_A = 25°C, V_S = ±15 V, R_F = 348 Ω, G = +1, and R_L = 2 kΩ (unless otherwise noted)



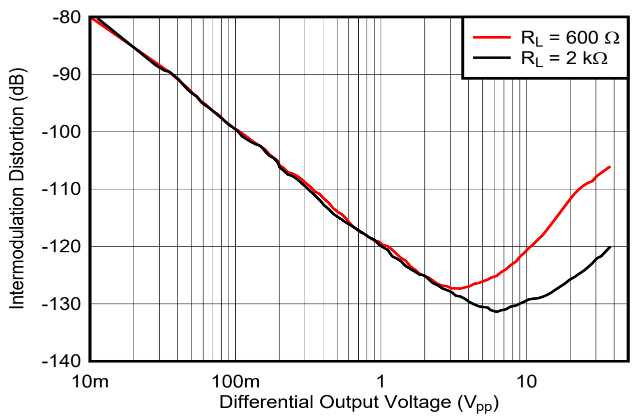
f = 250 kHz, single-ended input, differential output

图 6-13. Third-Harmonic Distortion vs Output Voltage



SMPTE 4:1: 60 Hz, 7 kHz; DIN 4:1: 250 Hz, 8 kHz, differential input/output

图 6-14. Intermodulation Distortion vs Output Voltage



SMPTE 4:1: 60 Hz, 7 kHz; DIN 4:1: 250 Hz, 8 kHz differential input/output

图 6-15. Intermodulation Distortion vs Output Voltage

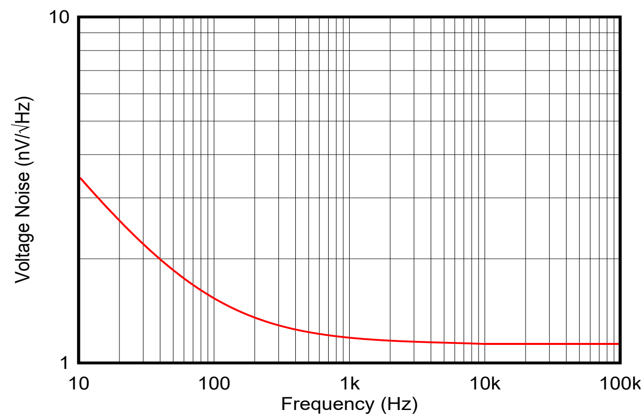


图 6-16. Voltage Noise vs Frequency

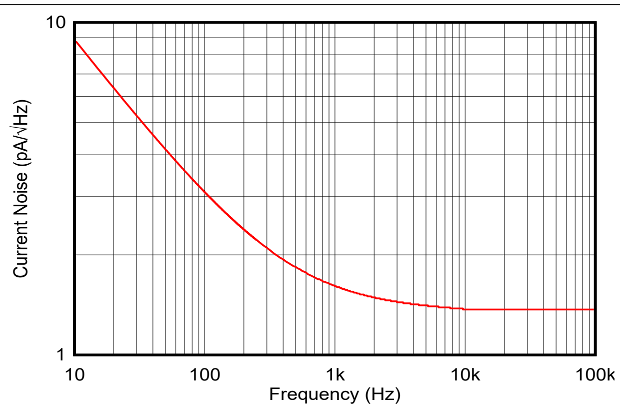
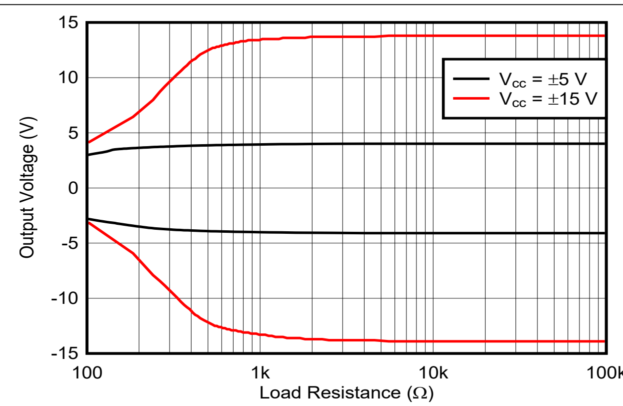


图 6-17. Current Noise vs Frequency



R_F = 1 kΩ, G = +2

图 6-18. Output Voltage vs Differential Load Resistance

6.6 Typical Characteristics (continued)

at T_A = 25°C, V_S = ±15 V, R_F = 348 Ω, G = +1, and R_L = 2 kΩ (unless otherwise noted)

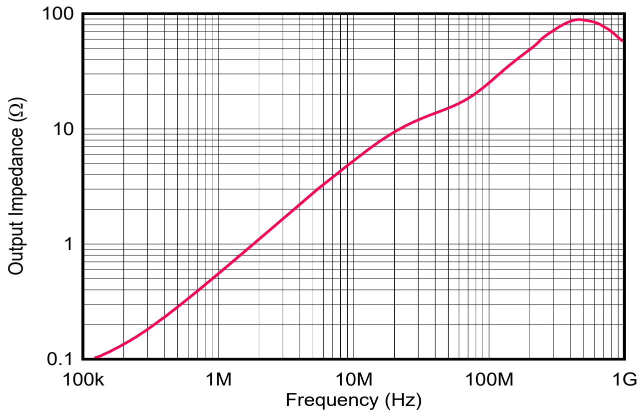


图 6-19. Output Impedance vs Frequency

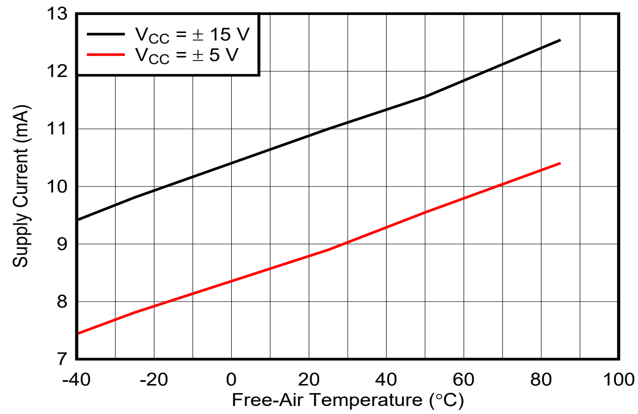


图 6-20. Supply Current vs Free-Air Temperature

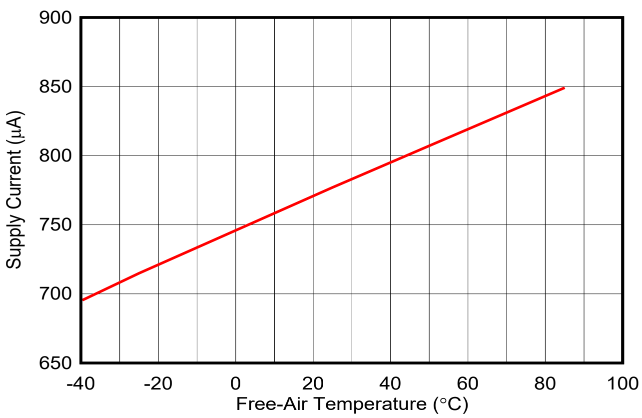


图 6-21. Supply Current vs Free-Air Temperature (Shutdown State)

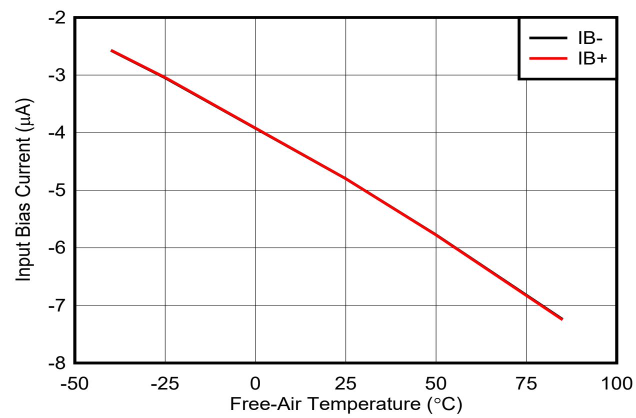
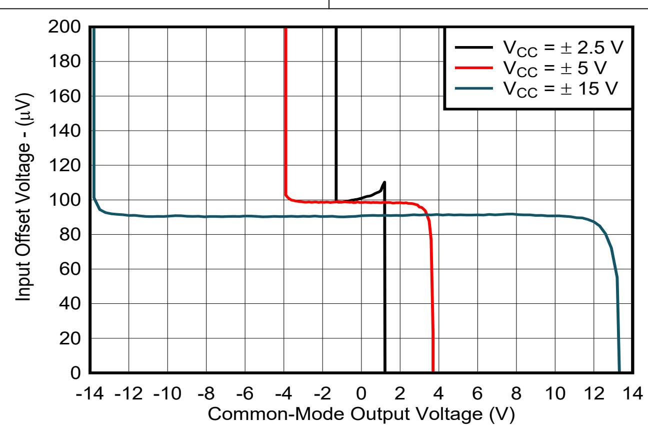


图 6-22. Input Bias Current vs Free-Air Temperature



R_F = 1 kΩ

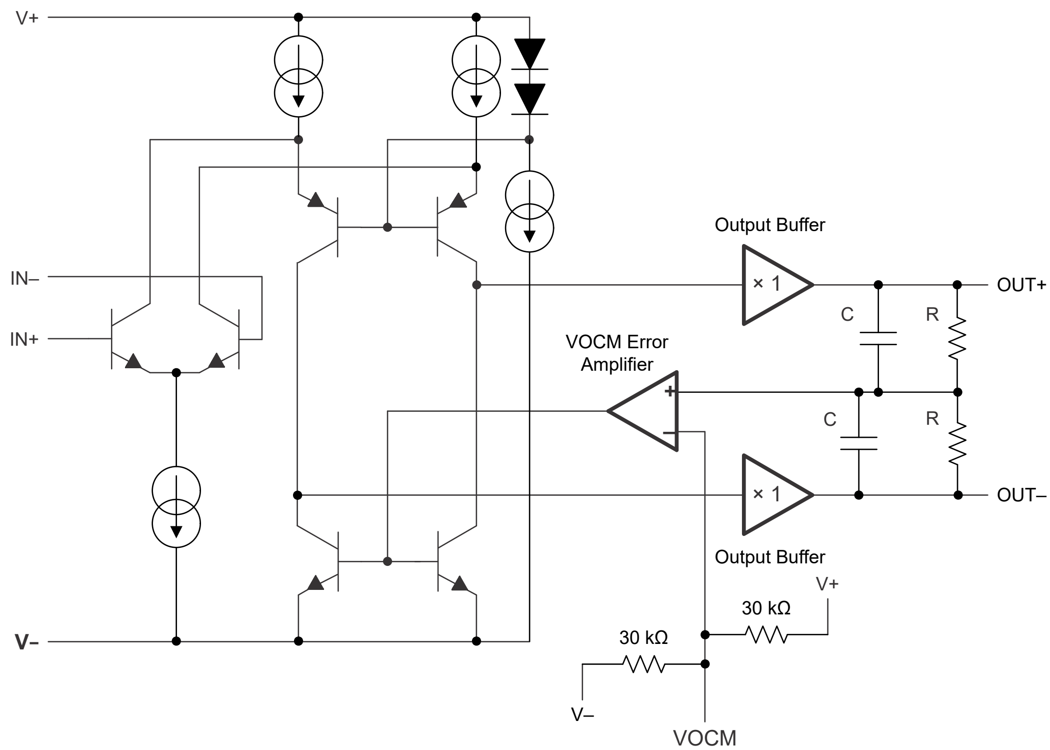
图 6-23. Input Offset Voltage vs Common-Mode Output Voltage

7 Detailed Description

7.1 Overview

The OPA1633 is a fully differential amplifier (FDA). Differential signal processing offers a number of performance advantages in high-speed analog signal processing systems, including immunity to external common-mode noise, suppression of even-order nonlinearities, and increased dynamic range. FDAs not only serve as the primary means of providing gain to a differential signal chain, but also provide a monolithic solution for converting single-ended signals into differential signals allowing for easy, high-performance processing. For more information on the basic theory of operation for FDAs, refer to the *Fully Differential Amplifiers* application note.

7.2 Functional Block Diagram



7.3 Feature Description

图 7-1 and 图 7-2 depict the differences between the operation of the OPA1633 in two different modes. FDAs can work with a differential input or be implemented as a single-ended input and differential output.

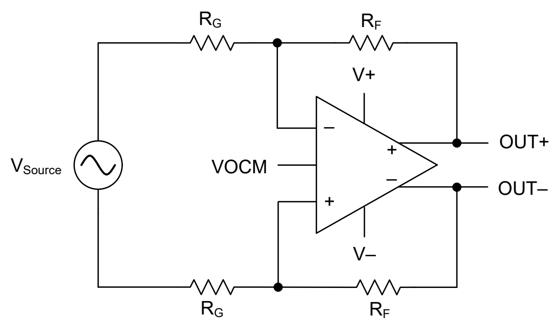


图 7-1. Amplifying Differential Input Signals

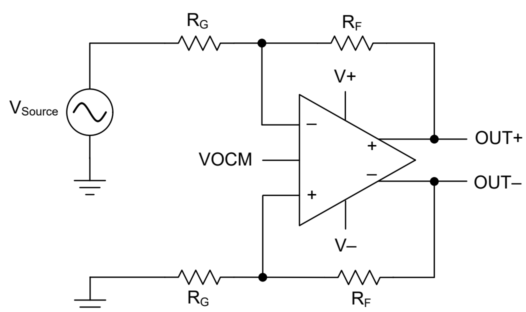


图 7-2. Amplifying Single-Ended Input Signals

7.4 Device Functional Modes

7.4.1 Shutdown Function

The shutdown (enable) function of the OPA1633 is referenced to the negative supply of the operational amplifier. A valid logic low (< 0.8 V above negative supply) applied to the Enable pin (pin 7) disables the amplifier output. Voltages applied to pin 7 that are greater than 2 V above the negative supply place the amplifier output in an active state, and the device is enabled. If pin 7 is left disconnected, an internal pullup resistor enables the device. Turn-on and turn-off times are approximately 2 μs each.

Quiescent current is reduced to approximately 0.77 mA when the amplifier is disabled. When disabled, the output stage is *not* in a high-impedance state. Thus, the shutdown function cannot be used to create a multiplexed switching function in series with multiple amplifiers.

8 Application and Implementation

备注

以下应用部分中的信息不属于 TI 元件规格，TI 不担保其准确性和完整性。TI 的客户负责确定元件是否适合其用途，以及验证和测试其设计实现以确认系统功能。

8.1 Application Information

8.1.1 Output Common-Mode Voltage

The output common-mode voltage pin sets the dc output voltage of the OPA1633. A voltage applied to the VOCM pin from a low-impedance source can be used to directly set the output common-mode voltage. If left floating, the VOCM pin defaults to the mid-rail voltage, defined as:

$$\frac{(V+) + (V-)}{2} \tag{1}$$

To minimize common-mode noise, connect a 0.1-uF bypass capacitor to the VOCM pin. Output common-mode voltage causes additional current to flow in the feedback resistor network. This current is supplied by the output stage of the amplifier; therefore, additional power dissipation is created. For commonly used feedback resistance values, this current is easily supplied by the amplifier. The additional internal power dissipation created by this current can be significant in some applications and can dictate use of the HVSSOP (DGN) PowerPAD integrated circuit package to effectively control self-heating.

8.1.1.1 Resistor Matching

Resistor matching is important in FDAs to maintain good output balance. An ideal differential output signal implies the two outputs of the FDA should be exactly equal in amplitude and shifted 180° in phase. Any imbalance in amplitude or phase between the two output signals results in an undesirable common-mode signal at the output. The output balance error is a measure of how well the outputs are balanced and is defined as the ratio of the output common-mode voltage to the output differential signal.

$$\text{Output Balance Error} = \frac{\left(\frac{(V_{OUT+}) - (V_{OUT-})}{2}\right)}{(V_{OUT+}) - (V_{OUT-})} \tag{2}$$

At low frequencies, resistor mismatch is the primary contributor to output balance errors. Additionally CMRR, PSRR, and HD2 performance diminish if resistor mismatch occurs. Therefore, use 1% tolerance resistors or better to optimize performance. 表 8-1 provides the recommended resistor values to use for a particular gain.

表 8-1. Recommended Resistor Values

GAIN (V/V)	R_G (Ω)	R_F (Ω)
1	390	390
2	374	750
5	402	2010
10	402	4020

8.2 Typical Application

图 8-1 shows the OPA1633 used as a differential-output driver for the PCM1804 high-performance audio ADC.

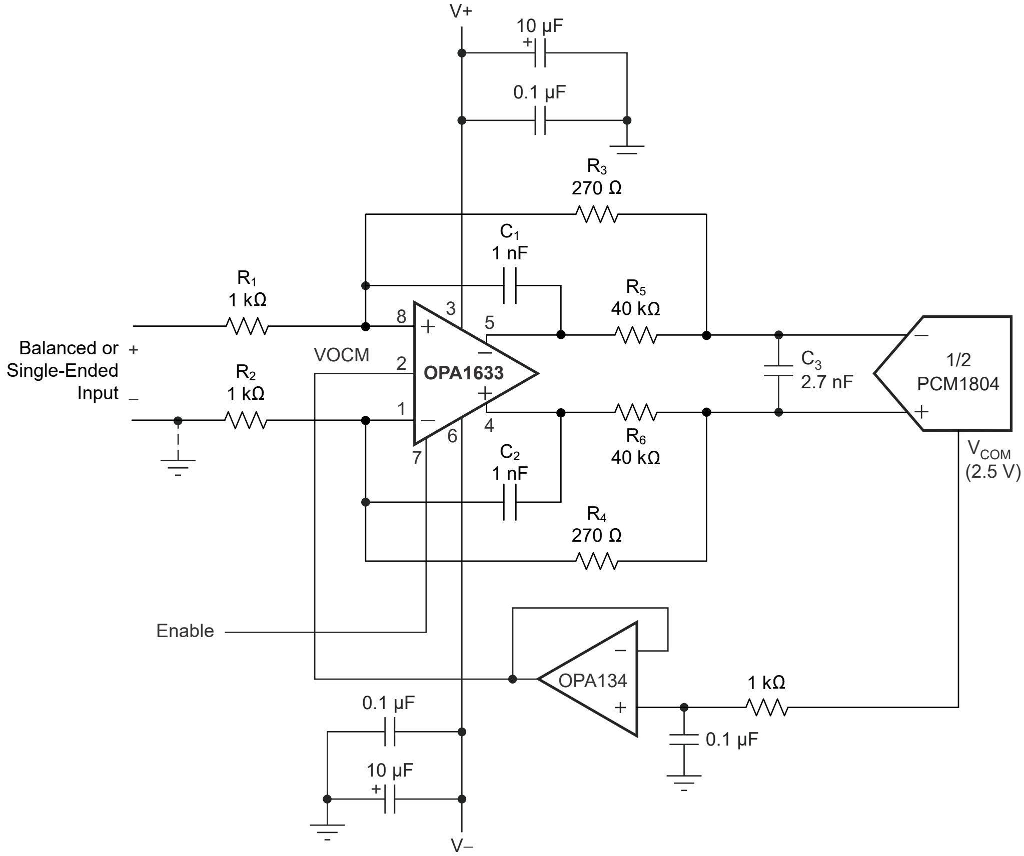


图 8-1. ADC Driver for Professional Audio

8.2.1 Design Requirements

表 8-2 provides example design parameters and values for the typical application design example shown in 图 7-1.

表 8-2. Design Parameters

DESIGN PARAMETERS	VALUE
Supply voltage	±2.5 V to ±17.5 V
Amplifier topology	Voltage feedback
Output control	DC-coupled with output common-mode control capability
Filter requirement	500-kHz, multiple-feedback low-pass filter

8.2.2 Detailed Design Procedure

Supply voltages of ±15 V are commonly used for the OPA1633. The relatively low input voltage swing required by the ADC allows use of lower power-supply voltage, if desired. Power supplies as low as ±8 V can be used in this application with excellent performance. This lower-voltage operation reduces power dissipation and heat rise. Bypass power supplies with 10-μF tantalum capacitors in parallel with 0.1-μF ceramic capacitors to avoid possible oscillations and instability.

The V_{COM} reference voltage output on the PCM1804 ADC provides the proper input common-mode reference voltage (2.5 V). This V_{COM} voltage is buffered with op amp by the OPA134 and drives the output common-mode voltage pin of the OPA1633. This biases the average output voltage of the OPA1633 to 2.5 V.

The signal gain of the circuit is generally set to approximately 0.25 to be compatible with commonly used audio line levels. Gain can be adjusted, if necessary, by changing the values of R_1 and R_2. Keep the feedback resistor values (R_3 and R_4) relatively low, as indicated, for best noise performance.

Resistors R_5, R_6, and C_3 provide an input filter and charge glitch reservoir for the ADC. The values shown are generally satisfactory. Some adjustment of the values can help optimize performance with different ADCs.

Make sure to maintain accurate resistor matching on R_1/R_2 and R_3/R_4 to achieve good differential signal balance. Use 1% resistors for highest performance. When connected for single-ended inputs (inverting input grounded, see 图 8-1), the source impedance must be low. Differential input sources must have well-balanced or low source impedance.

Choose capacitors C_1, C_2, and C_3 carefully for good distortion performance. Polystyrene, polypropylene, NPO ceramic, and mica types are generally excellent. Polyester and high-K ceramic types such as Z5U can create distortion.

8.2.3 Application Curves

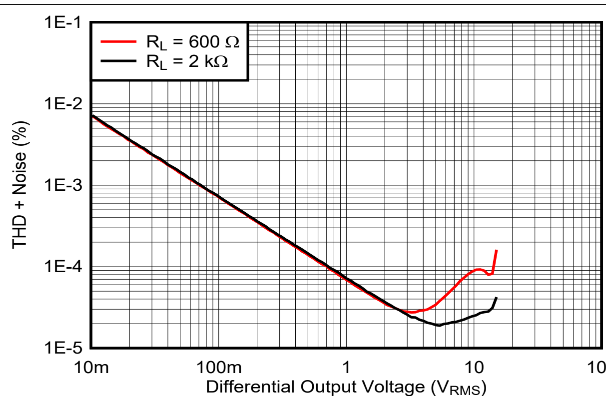


图 8-2. THD + Noise vs Output Voltage

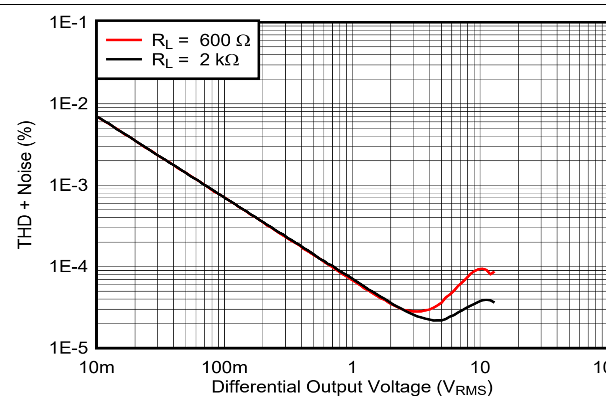


图 8-3. THD + Noise vs Output Voltage

8.3 Power Supply Recommendations

The OPA1633 device is designed to operate on power supplies ranging from ±2.5 V to ±17.5 V. Single power supplies ranging from 5 V to 35 V can also be used. Use a power-supply accuracy of 5%, or better. When operated on a board with high-speed digital signals, make sure to provide isolation between digital signal noise and the analog input pins. The OPA1633 is connected to power supplies through pin 3 (V+) and pin 6 (V−). Decouple each supply pin to GND as close to the device as possible with a low-inductance, surface-mount ceramic capacitor of approximately 10 nF. When vias are used to connect the bypass capacitors to a ground plane, configure the vias for minimal parasitic inductance. One method of reducing via inductance is to use multiple vias. For broadband systems, two capacitors per supply pin are advised.

To avoid undesirable signal transients, do not power on the OPA1633 device with large inputs signals present. Careful planning of system power on sequencing is especially important to avoid damage to ADC inputs when an ADC is used in the application.

8.4 Layout

8.4.1 Layout Guidelines

1. The thermal pad is electrically isolated from the silicon and all leads. Connecting the thermal pad to any potential voltage between the power-supply voltages is acceptable; however, best practice is to tie to ground because ground is generally the largest conductive plane.
2. Prepare the printed circuit board (PCB) with a top-side etch pattern, as shown in 图 8-4. Use etch for the leads as well as etch for the thermal pad.
3. Place five holes in the area of the thermal pad. Keep these holes 13 mils (0,03302 cm) in diameter. Keep them small so that solder wicking through the holes is not a problem during reflow.
4. Additional vias can be placed anywhere along the thermal plane outside of the thermal pad area. These vias help dissipate the heat generated by the OPA1633 device, and can be larger than the 13-mil diameter vias directly under the thermal pad. The vias can be larger because the vias are not in the thermal pad area to be soldered so that wicking is not a problem.
5. Connect all holes to the internal ground plane.
6. When connecting these holes to the plane, do not use the typical web or spoke via connection methodology. Web connections have a high thermal resistance connection that is useful for slowing the heat transfer during soldering operations. This slow heat transfer makes the soldering of vias that have plane connections easier. In this application, however, low thermal resistance is desired for the most efficient heat transfer. Therefore, make sure the holes under the OPA1633 PowerPAD package connect to the internal plane with a complete connection around the entire circumference of the plated through-hole.
7. The top-side solder mask must leave the package pins and the thermal pad area with the five holes exposed. The bottom-side solder mask must cover the five holes of the thermal pad area. This configuration prevents solder from being pulled away from the thermal pad area during the reflow process.
8. Apply solder paste to the exposed thermal pad area and all of the device pins.

   With these preparatory steps in place, the device is simply placed in position and runs through the solder reflow operation as any standard surface-mount component. This process results in a part that is properly installed.

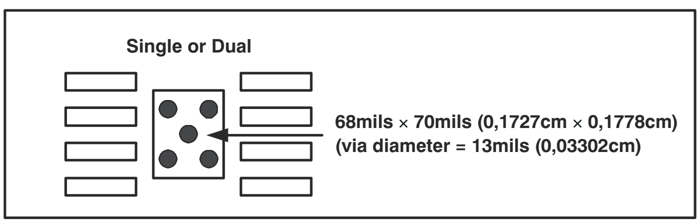


图 8-4. PowerPAD Integrated Circuit Package PCB Etch and Via Pattern

8.4.1.1 PowerPAD™ Integrated Circuit Package Design Considerations

The OPA1633 is available in a thermally-enhanced PowerPAD integrated circuit package. This package is constructed using a downset leadframe upon which the die is mounted (see 图 8-5(a) and 图 8-5(b)). This arrangement results in the lead frame being exposed as a thermal pad on the underside of the package (see 图 8-5(c)). Because this thermal pad has direct thermal contact with the die, excellent thermal performance can be achieved by providing a good thermal path away from the thermal pad.

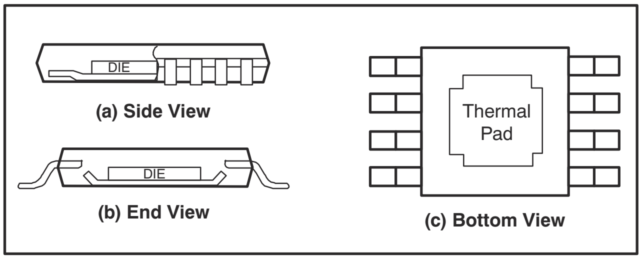


图 8-5. Views of the Thermally-Enhanced Package

The PowerPAD integrated circuit package allows for both assembly and thermal management in one manufacturing operation. During the surface-mount solder operation (when the leads are being soldered), the thermal pad must be soldered to a copper area underneath the package. Through the use of thermal paths within this copper area, heat can be conducted away from the package into either a ground plane or other heat-dissipating device. Soldering the thermal pad to the PCB is always required, even with applications that have low power dissipation. The PowerPAD integrated circuit package provides the necessary thermal and mechanical connection between the lead frame die pad and the PCB.

8.4.1.2 Power Dissipation and Thermal Considerations

The OPA1633 does not have thermal shutdown protection. Make sure that the maximum junction temperature is not exceeded. Excessive junction temperature can degrade performance or cause permanent damage. For best performance and reliability, make sure that the junction temperature does not exceed 125°C.

The thermal characteristics of the device are dictated by the package and the circuit board. Maximum power dissipation for a given package can be calculated using the following formula:

$$P_{DMax} = \frac{T_{Max} - T_A}{\theta_{JA}} \quad (3)$$

where:

- P_{DMax} is the maximum power dissipation in the amplifier (W)
- T_{Max} is the absolute maximum junction temperature (°C)
- T_A is the ambient temperature (°C)
- $\theta_{JA} = \theta_{JC} + \theta_{CA}$
- θ_{JC} is the thermal coefficient from the silicon junctions to the case (°C/W)
- θ_{CA} is the thermal coefficient from the case to ambient air (°C/W)

For systems where heat dissipation is more critical, the OPA1633 is offered in an HVSSOP-8 with PowerPAD integrated circuit package. The thermal coefficient for the HVSSOP (DGN) package is substantially improved over the traditional SO package.

8.4.2 Layout Example

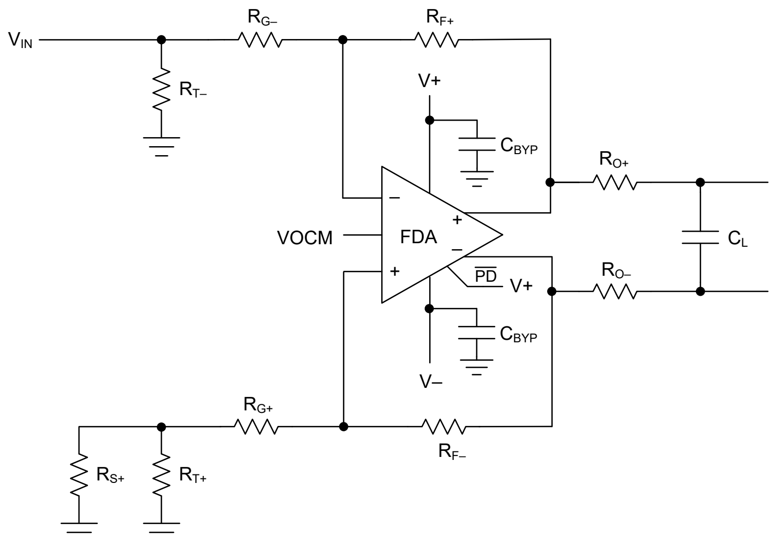


图 8-6. Representative Schematic for Example Layout

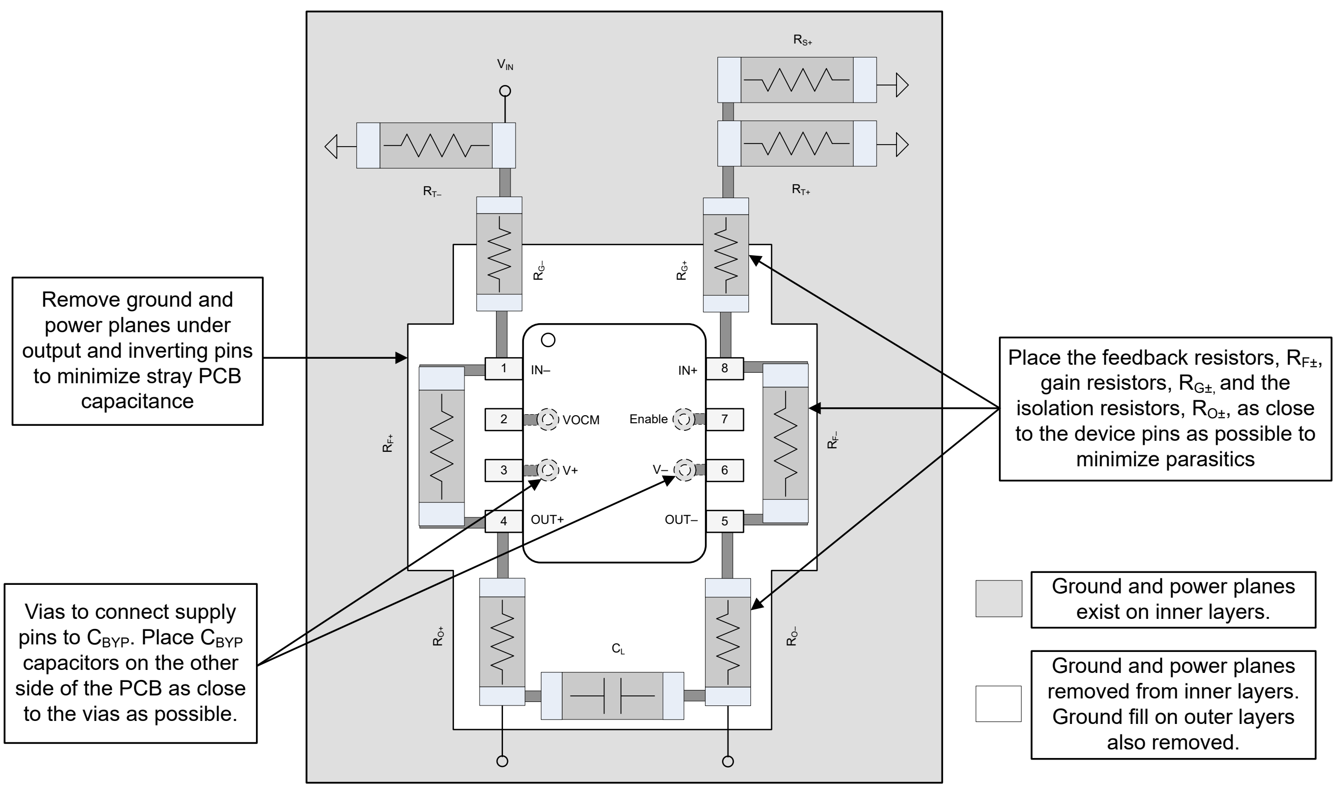


图 8-7. Example Layout

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, *Fully Differential Amplifiers* application note
- Texas Instruments, *TI Precision Labs - Fully Differential Amplifiers* video series
- Texas Instruments, *Maximizing Signal Chain Distortion Performance Using High Speed Amplifiers* application note
- Texas Instruments, *Analog Audio Amplifier Front-End Reference Design With Improved Noise and Distortion*
- Texas Instruments, *Public Announcement Audio Reference Design utilizing Best in Class Boost Controller*
- Texas Instruments, *Motherboard/controller for the AMC1210* Reference Design
- Texas Instruments,*TPA6120A2 Stereo, 9.0 to 33.0-V, Analog Input Headphone Amplifier With 128-dB Dynamic Range*
- Texas Instruments, *OPA2863 Dual, Low-Power, 110-MHz, 12-V, RRIO Voltage Feedback Amplifier*
- Texas Instruments, *OPA2834 Ultra-Low Power, 50-MHz Rail-to-Rail Out, Negative Rail In, Voltage-feedback Op Amp*

9.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

9.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

9.4 Trademarks

PowerPAD™ and TI E2E™ are trademarks of Texas Instruments.
所有商标均为其各自所有者的财产。

9.5 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

9.6 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
OPA1633DGNR	ACTIVE	HVSSOP	DGN	8	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	2USJ	Samples
OPA1633DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	O1633	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

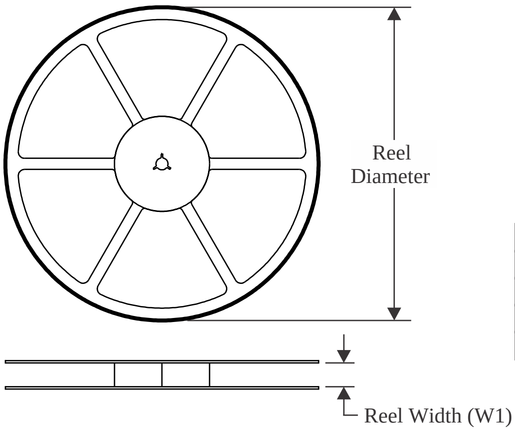
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

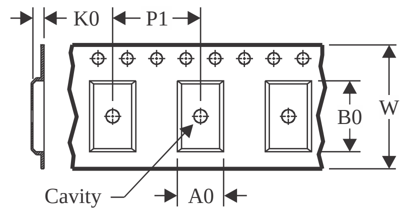
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

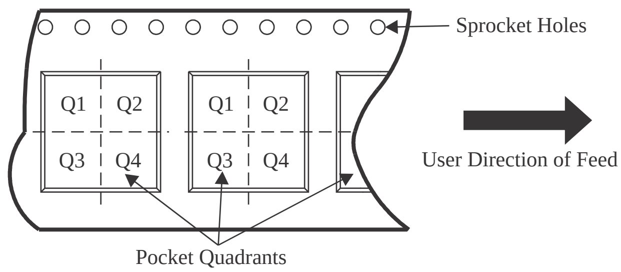


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

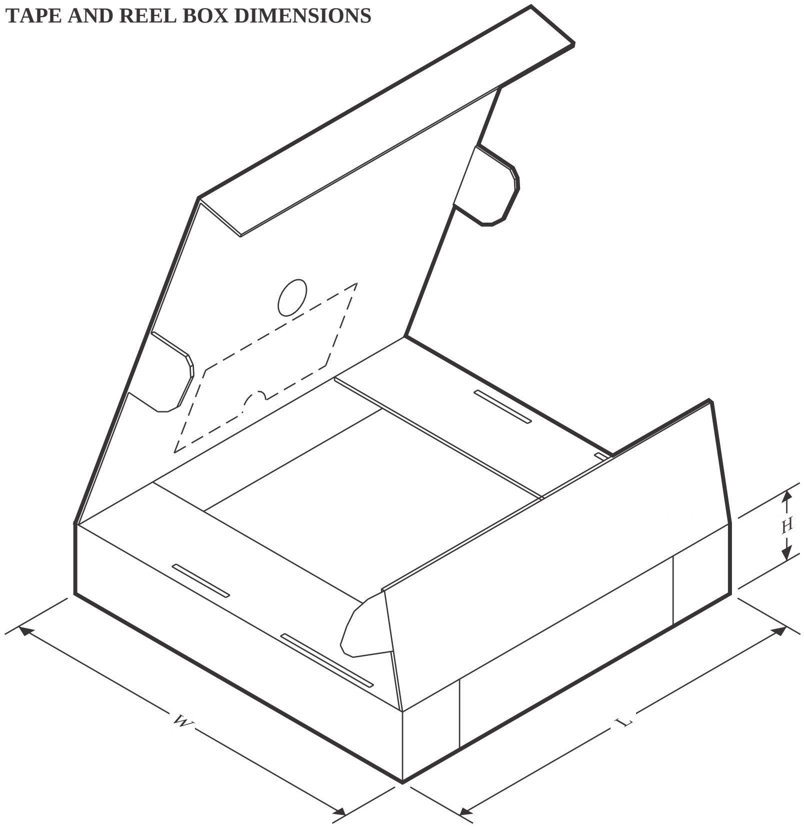
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA1633DGNR	HVSSOP	DGN	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA1633DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA1633DGNR	HVSSOP	DGN	8	2500	356.0	356.0	35.0
OPA1633DR	SOIC	D	8	2500	356.0	356.0	35.0

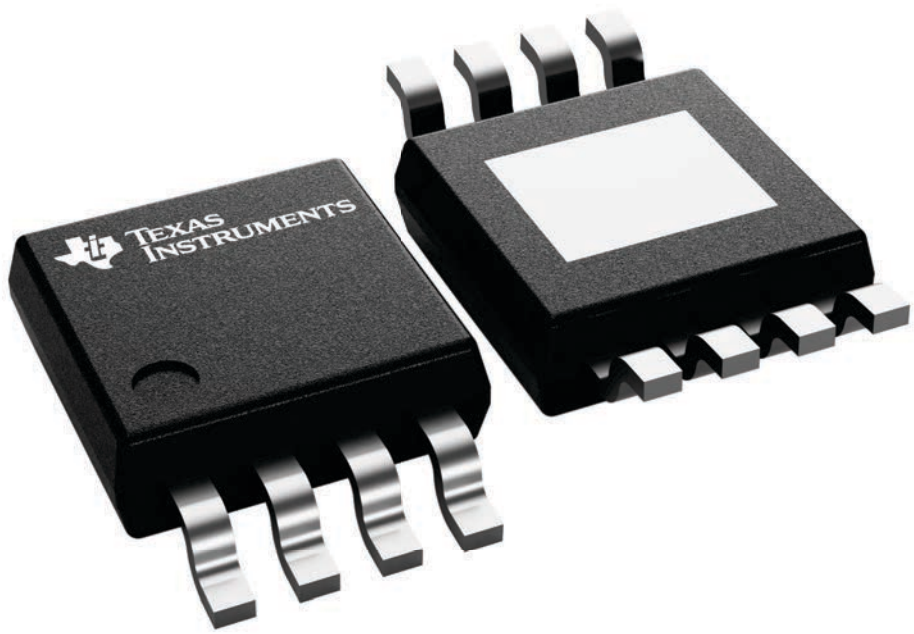
DGN 8

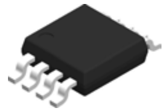
PowerPAD™ HVSSOP - 1.1 mm max height

3 x 3, 0.65 mm pitch

SMALL OUTLINE PACKAGE

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

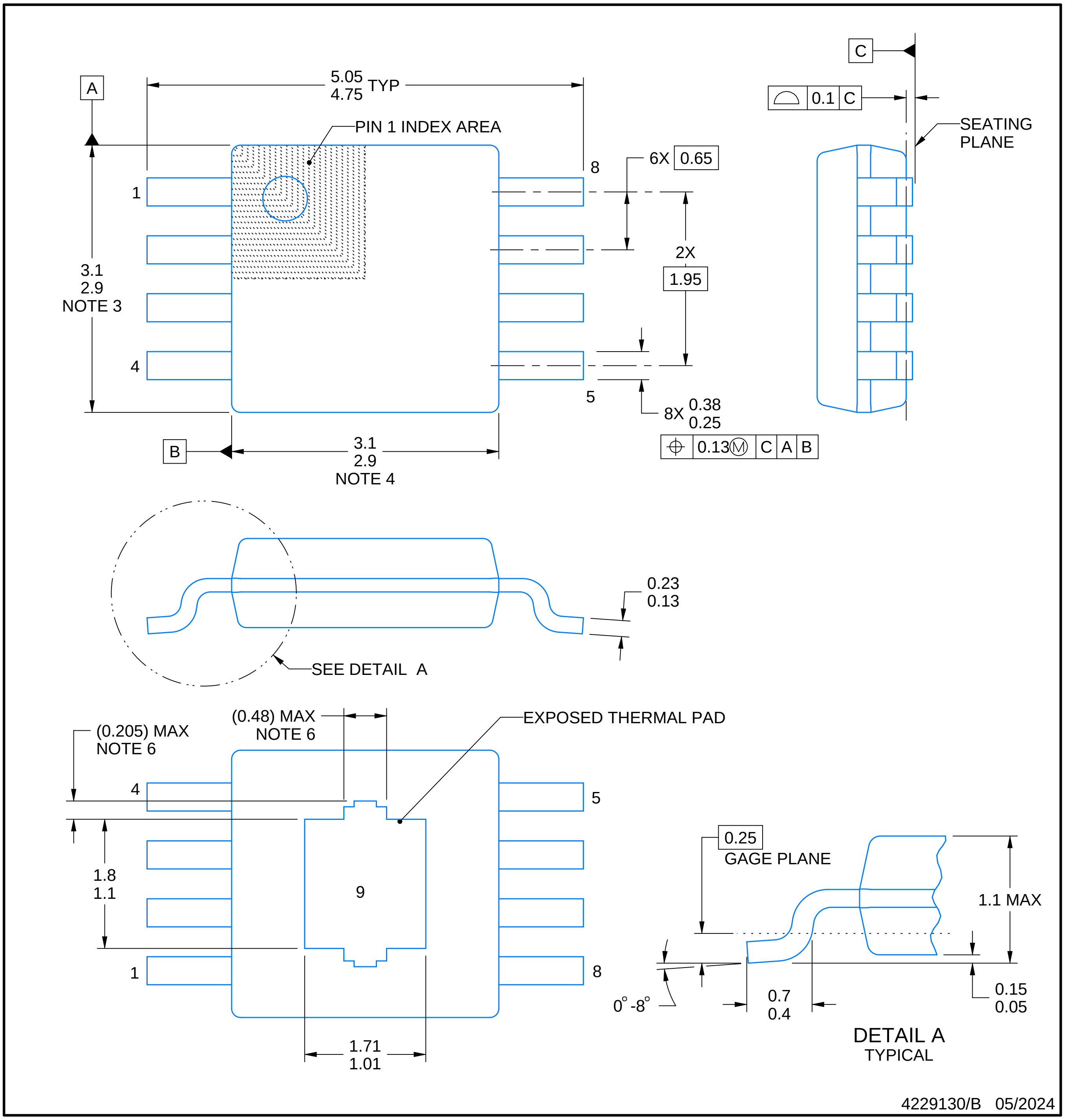




PACKAGE OUTLINE

PowerPAD™ VSSOP - 1.1 mm max height

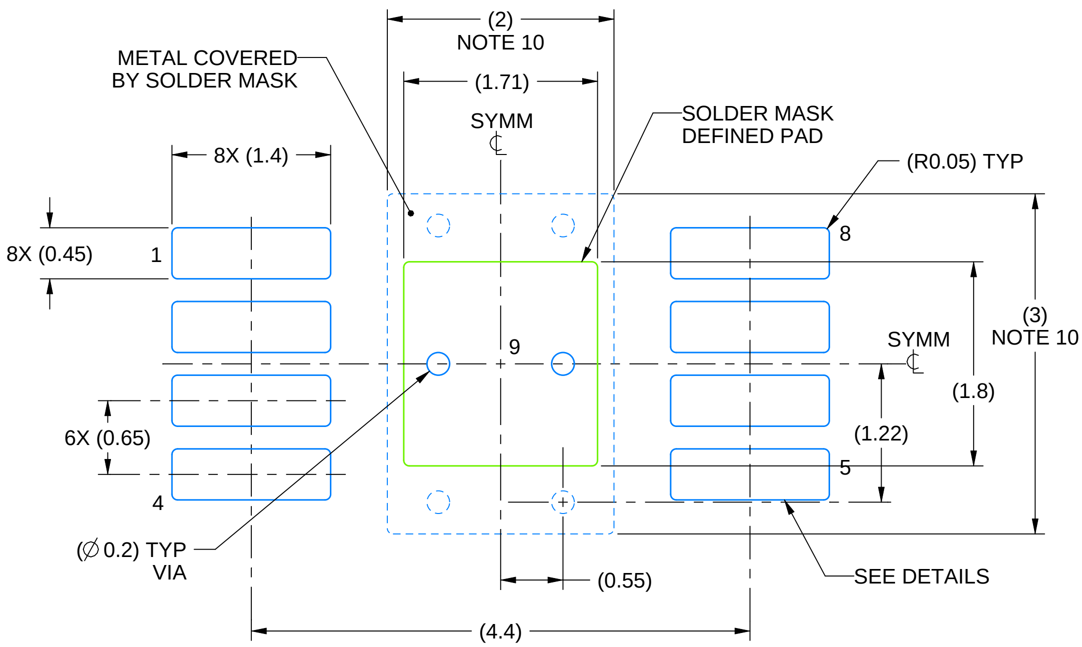
SMALL OUTLINE PACKAGE



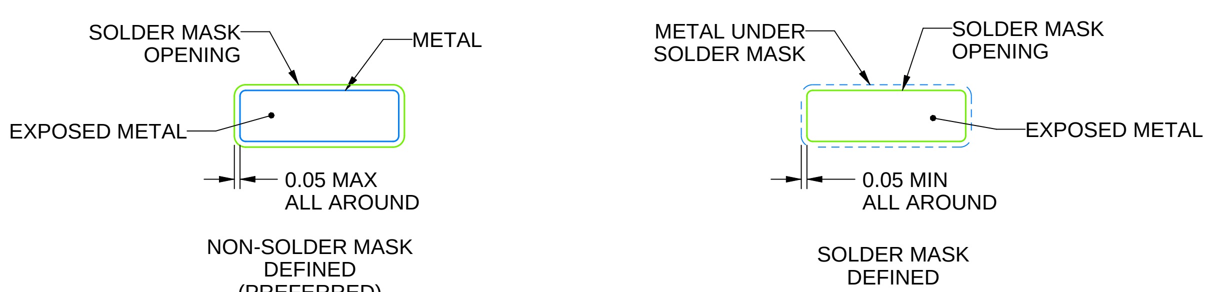
NOTES:

PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.
6. Features may differ or may not be present.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X

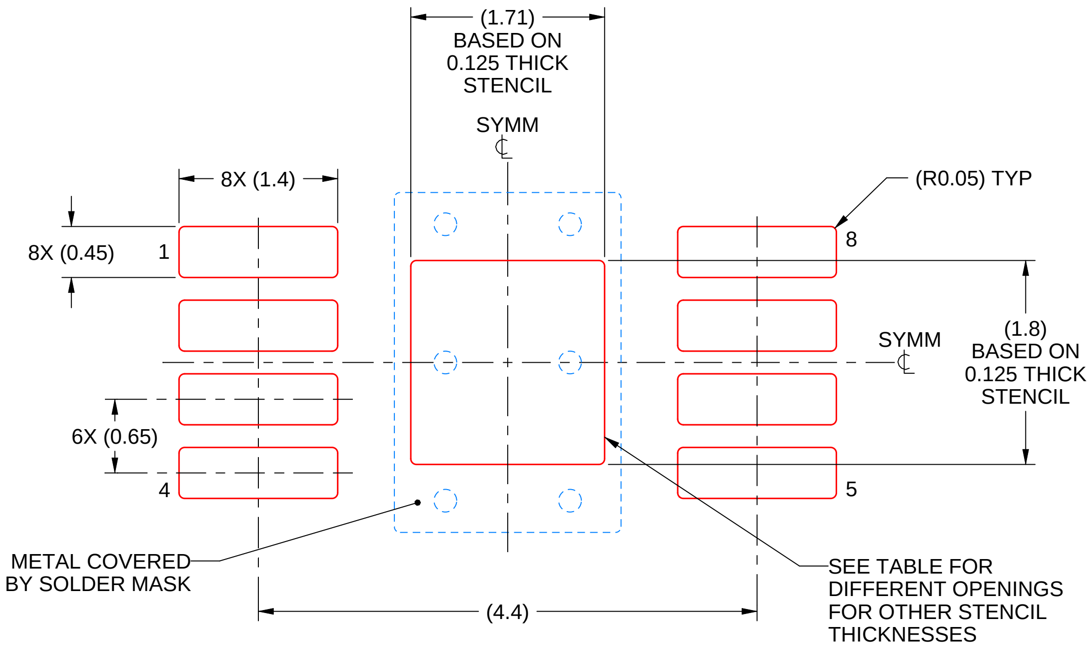


SOLDER MASK DETAILS

4229130/B 05/2024

NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
9. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
10. Size of metal pad may vary due to creepage requirement.



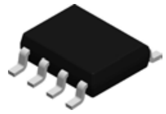
SOLDER PASTE EXAMPLE
EXPOSED PAD 9:
100% PRINTED SOLDER COVERAGE BY AREA
SCALE: 15X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	1.91 X 2.01
0.125	1.71 X 1.80 (SHOWN)
0.15	1.56 X 1.64
0.175	1.45 X 1.52

4229130/B 05/2024

NOTES: (continued)

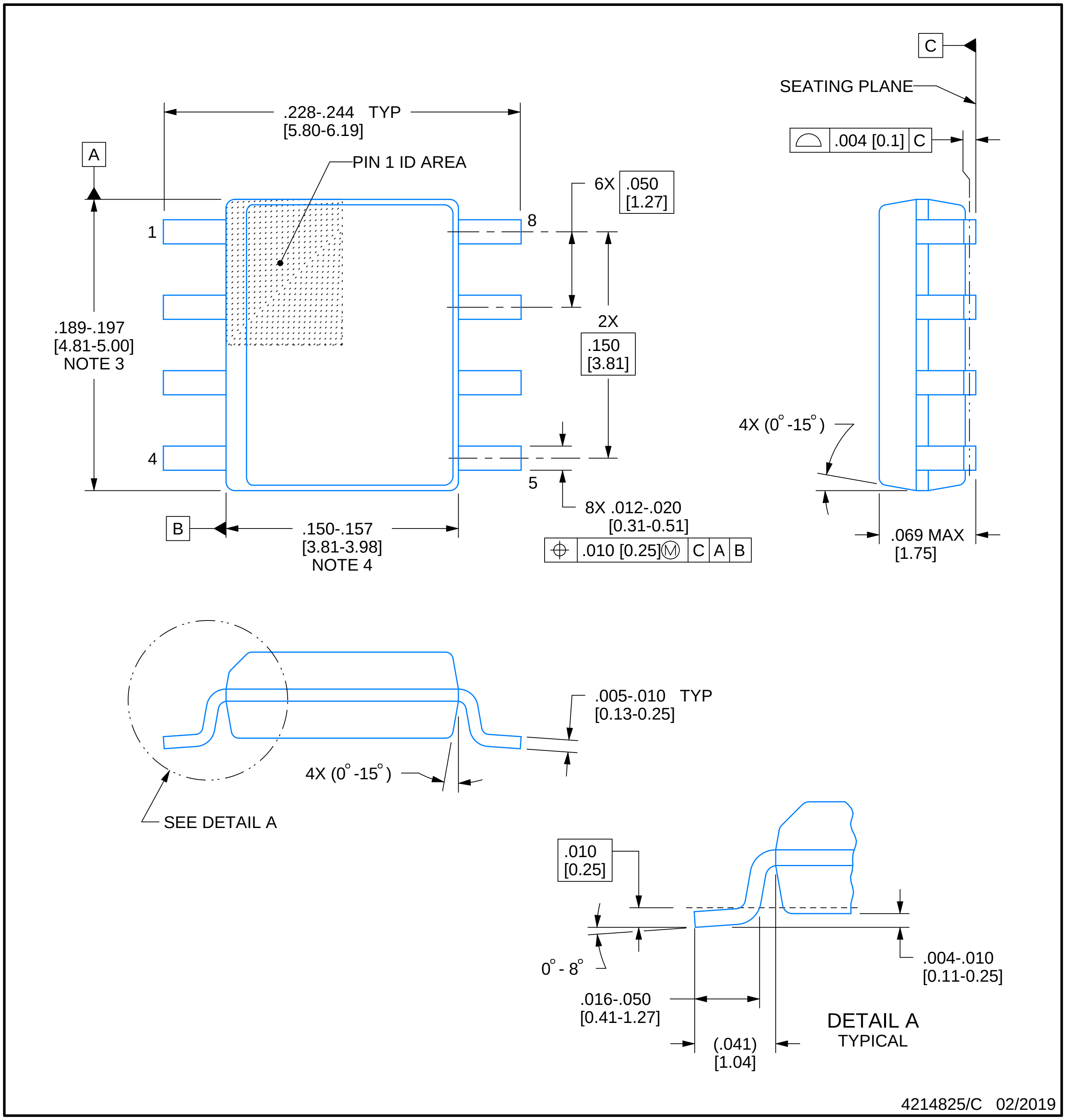
11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.



D0008A

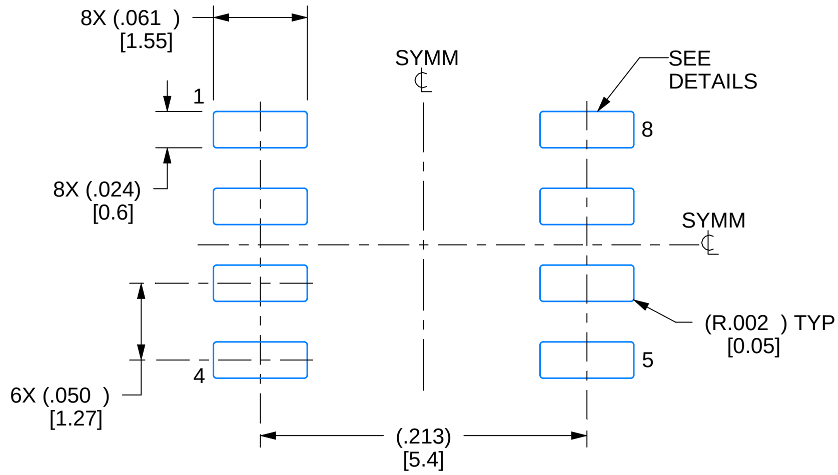
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

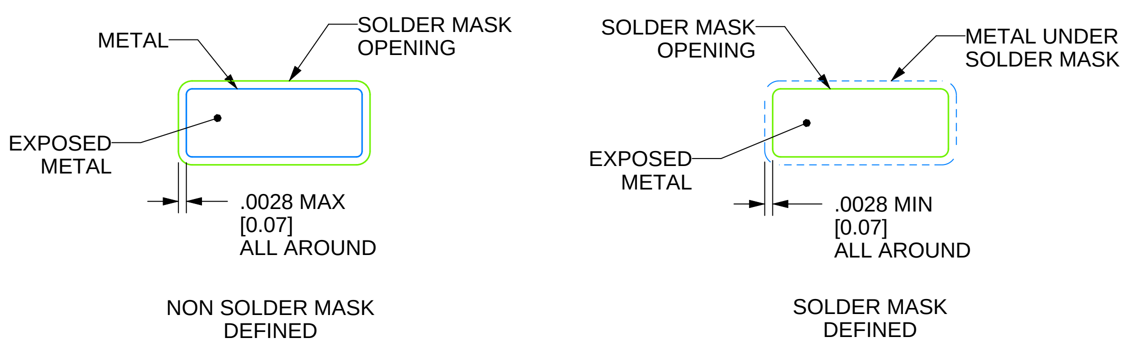


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

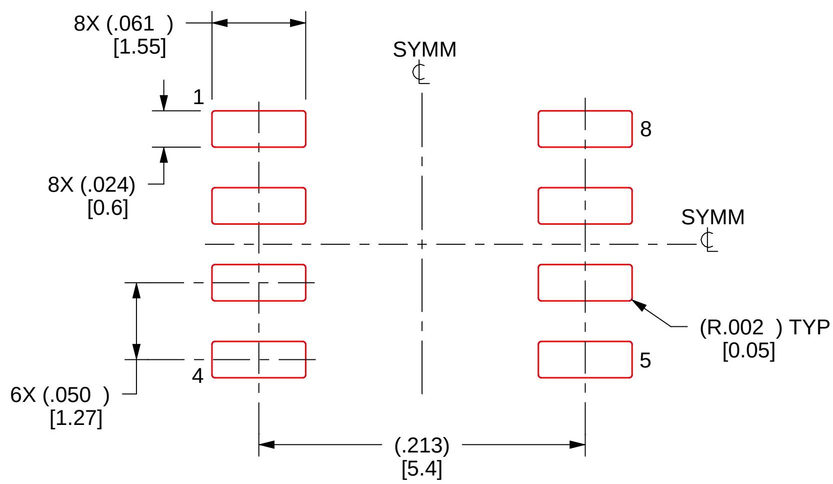


SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要声明和免责声明

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265